



SOLID STATE DEVICES, INC

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## Designer's Data Sheet

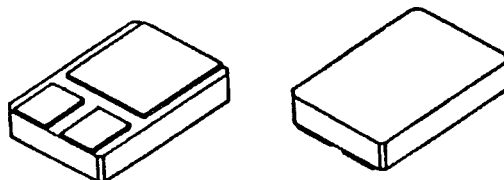
## FEATURES:

- Rugged construction with poly silicon gate
- Low RDS(on) and high transconductance
- Excellent high temperature stability
- Very fast switching speed
- Fast recovery and superior dv/dt performance
- Increased reverse energy capability
- Low input and transfer capacitance for easy paralleling
- Hermetically sealed surface mount power package
- TX, TXV and Space Level screening available
- Replaces: IRF340 Types

SFF340

**10 AMP  
400 VOLTS  
0.55Ω  
N-CHANNEL  
POWER MOSFET**

## MILPACK



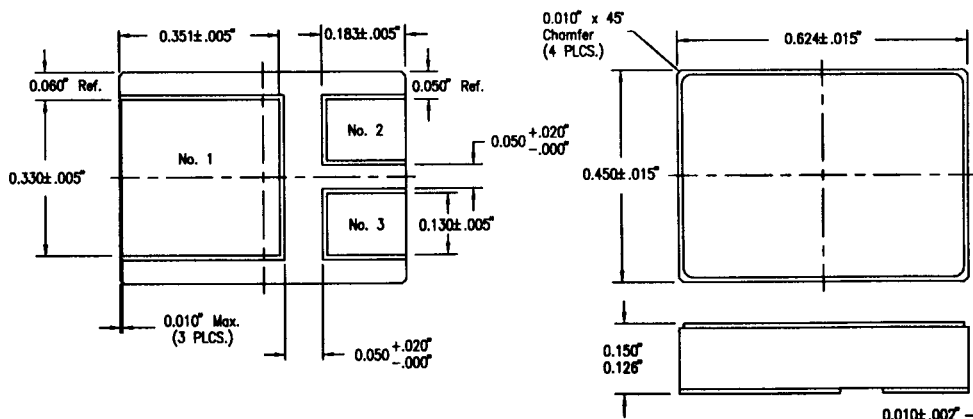
## MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	VALUE	UNIT
Drain to Source Voltage	V <sub>DS</sub>	400	Volts
Gate to Source Voltage	V <sub>GS</sub>	±20	Volts
Continuous Drain Current	I <sub>D</sub>	10	Amps
Operating and Storage Temperature	Top & Tstg	-55 to +150	°C
Thermal Resistance, Junction to Case	RθJC	1.7	°C/W
Total Device Dissipation @ TC=25°C	P <sub>D</sub>	79	Watts
Total Device Dissipation @ TC=55°C		55	

## PACKAGE OUTLINE: MILPACK

## PIN OUT:

**PIN 1: DRAIN  
PIN 2: SOURCE  
PIN 3: GATE**



**NOTE:** All specifications are subject to change without notification. SCD's for these devices should be reviewed by SSDI prior to release.

DATA SHEET #: F00071 B

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**ELECTRICAL CHARACTERISTICS @ T<sub>J</sub>=25 °C (Unless Otherwise Specified)**

RATING		SYMBOL	MIN	TYP	MAX	UNIT
<b>Drain to Source Breakdown Voltage</b> (V <sub>GS</sub> =0 V, I <sub>D</sub> =250μA)		BV <sub>DSS</sub>	400	---	---	V
<b>Drain to Source on State Resistance</b> (V <sub>GS</sub> =10 V, I <sub>D</sub> =60% Rated ID)		R <sub>DS(on)</sub>	---	0.42	0.55	Ω
<b>On State Drain Current</b> (V <sub>DS</sub> > I <sub>D(on)</sub> X R <sub>DS(on)</sub> Max, V <sub>GS</sub> =10 V)		I <sub>D(on)</sub>	10	---	---	A
<b>Gate Threshold Voltage</b> (V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA)		V <sub>GS(th)</sub>	2.0	---	4.0	V
<b>Forward Transconductance</b> (V <sub>DS</sub> ≥ 50V, I <sub>DS</sub> =60% rated ID)		g <sub>fs</sub>	5.8	8.7	---	S(Ω)
<b>Zero Gate Voltage Drain Current</b> (V <sub>DS</sub> =max rated voltage, V <sub>GS</sub> =0 V) (V <sub>DS</sub> =80% rated V <sub>DS</sub> , V <sub>GS</sub> =0 V, T <sub>A</sub> =125°C)		I <sub>DSS</sub>	---	---	250 1000	μA
<b>Gate to Source Leakage Forward</b> <b>Gate to Source Leakage Reverse</b>	At rated V <sub>GS</sub>	I <sub>GSS</sub>	---	---	100 -100	nA
<b>Total Gate Charge</b> <b>Gate to Source Charge</b> <b>Gate to Drain Charge</b>	V <sub>GS</sub> =10 Volts 80% rated V <sub>DS</sub> I <sub>D</sub> =10A	Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	---	43 6 22	65 9.3 33	nC
<b>Turn on Delay Time</b> <b>Rise Time</b> <b>Turn Off Delay Time</b> <b>Fall Time</b>	V <sub>DD</sub> =50% rated V <sub>DS</sub> I <sub>D</sub> =10A R <sub>G</sub> =9.1Ω R <sub>D</sub> =20Ω	t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub>	---	14 27 50 24	9 30 74 36	nsec
<b>Diode Forward Voltage</b> (I <sub>S</sub> =rated I <sub>D</sub> , V <sub>GS</sub> =0 V, T <sub>J</sub> =25°C)		V <sub>SD</sub>	---	---	2.0	V
<b>Diode Reverse Recovery Time</b> <b>Reverse Recovery Charge</b>	T <sub>J</sub> =25°C I <sub>F</sub> =rated I <sub>D</sub> di/dt=100 A/μsec	t <sub>rr</sub> Q <sub>RR</sub>	170 1.6	370 3.8	790 8.2	nsec μC
<b>Input Capacitance</b> <b>Output Capacitance</b> <b>Reverse Transfer Capacitance</b>	V <sub>GS</sub> =0 Volts V <sub>DS</sub> =25 Volts f=1 MHz	C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	---	1300 210 37	---	pF

SAFE OPERATING AREA (S.O.A.)  
T<sub>C</sub> = 25 °C, D.C. CONDITION